



Material Content Data Sheet



Sales Product Name				IKB06N60T		Issued		24. January 2018	
MA#				MA000960666					
Package				PG-TO263-3-2		Weight*		1556.57 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.019	0.06	0.06	632	632	
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		189		
	inorganic material	phosphorus	7723-14-0	0.091	0.01		57		
	non noble metal	copper	7440-50-8	304.026	18.87	18.90	188699	188945	
wire	non noble metal	aluminium	7429-90-5	1.435	0.09	0.09	891	891	
encapsulation	organic material	carbon black	1333-86-4	10.350	0.64		6424		
	plastics	epoxy resin	-	113.852	7.07		70665		
	inorganic material	silicondioxide	60676-86-0	565.812	35.13	42.84	351180	428269	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.60	0.60	5994	5994	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		142		
	inorganic material	phosphorus	7723-14-0	0.001	3.39	3.40	33888	34030	
solder	non noble metal	lead	7439-92-1	1.350	0.08		838		
	noble metal	silver	7440-22-4	0.035	0.00		22		
	non noble metal	tin	7440-31-5	0.028	0.00	0.08	18	878	
heatspreader	non noble metal	iron	7439-89-6	0.548	0.03		340		
	inorganic material	phosphorus	7723-14-0	0.165	0.01		102		
	non noble metal	copper	7440-50-8	547.666	33.99	34.03	339919	340361	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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